

ABSTRACT OF THE DISCLOSURE

Process solutions comprising one or more surfactants are used to reduce the
5 number of defects in the manufacture of semiconductor devices. In certain
embodiments, the process solution may reduce post-development defects such as
pattern collapse or line width roughness when employed as a rinse solution either during
or after the development of the patterned photoresist layer. Also disclosed is a method
for reducing the number of defects such as pattern collapse and/or line width roughness
10 on a plurality of photoresist coated substrates employing the process solution of the
present invention.